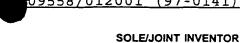
ORIGINAL/SUBSTITUTE/CIP



MOUNTING MULTIPLE SEMICONDUCTOR DIES IN A PACKAGE



As a below named inventor, I hereby declare that: my residence, post office address, and citizenship are as stated below next to my name. I believe I am the original, first, and sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Serial No.	pecification [x] att		patent Application
I hereby state that I have reviewed and amendment referred to above; that I do not our invention thereof, or patented or descrito this application; that the invention has not any country foreign to the United States of to this application; and that I acknowledge in accordance with Title 37, Code of Federa or being made of record in the application,	ot know and do not believe the same with the in any printed publication in any control of been patented or made the subject of America on an application filed by menthe duty to disclose information of which Regulations § 1.56(a). Such information and	as ever known or used in the lountry before my or our invention of an inventor's certificate issue or my legal representative or a shill am aware which is material on is material when it is not cum	United States of America before my or on thereof or more than one year prior d before the date of this application in assigns more than twelve months prior to the examination of this application ulative to information already of record
(2) it refutes, or is incons (i)	If or in combination with other informati istent with, a position the applicant ha opposing an argument of unpatentabili asserting an argument of patentability.	s taken or may take in:	atentability of a claim; or
I hereby claim foreign priority benefits under below and have also identified below any	er Title 35, United States Code § 119 o foreign application(s) having a filing da	f any foreign application(s) for te before that of the applicatio	patent or inventor's certificates listed n(s) on which priority is claimed:
COUNTRY	APPLICATION NUMBER	DATE OF FILING	PRIORITY CLAIMED UNDER 35 USC 119
<u> </u>			☐ YES ☐ NO
I hereby declare that all statements made he be true; and further that these statements wimpsisonment, or both, under Section 1001 capplication or any patent issued thereon.	were made with the knowledge that will	ful false statements and the like	te so made are punishable by fine or
FULL NAME OF SOLE OR FIRST INVENTOR	INVENTOR'S SIGNATURE	DA	TE
Salman Akram	Salva -	Akun	2/10/98
RESIDENCE		cn .	TZENSHIP
1463 E. Regatta St. Boise, Idaho 83706		Pa	akistan
1463 E. Regatta St. Boise, Idaho 83706			
FULL NAME OF SECOND JOINT INVENTOR	INVENTOR'S SIGNATURE	DA	TE .
RESIDENCE		СП	IZENSHIP
POST OFFICE ADDRESS			
6828.H11			